

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TMCS1133A1AQDVGRQ1	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133A1AQ1
TMCS1133A1AQDVGRQ1.A	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133A1AQ1
TMCS1133A2AQDVGRQ1	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133A2AQ1
TMCS1133A2AQDVGRQ1.A	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133A2AQ1
TMCS1133A3AQDVGRQ1	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133A3AQ1
TMCS1133A3AQDVGRQ1.A	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133A3AQ1
TMCS1133A4AQDVGRQ1	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133A4AQ1
TMCS1133A4AQDVGRQ1.A	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133A4AQ1
TMCS1133A5AQDVGRQ1	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133A5AQ1
TMCS1133A5AQDVGRQ1.A	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133A5AQ1
TMCS1133B1AQDVGRQ1	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133B1AQ1
TMCS1133B1AQDVGRQ1.A	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133B1AQ1
TMCS1133B2AQDVGRQ1	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133B2AQ1
TMCS1133B2AQDVGRQ1.A	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133B2AQ1
TMCS1133B3AQDVGRQ1	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133B3AQ1
TMCS1133B3AQDVGRQ1.A	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133B3AQ1
TMCS1133B4AQDVGRQ1	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133B4AQ1
TMCS1133B4AQDVGRQ1.A	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133B4AQ1
TMCS1133B5AQDVGRQ1	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133B5AQ1
TMCS1133B5AQDVGRQ1.A	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133B5AQ1
TMCS1133B7AQDVGRQ1	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133B7AQ1
TMCS1133B7AQDVGRQ1.A	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133B7AQ1
TMCS1133B8AQDVGRQ1	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133B8AQ1
TMCS1133B8AQDVGRQ1.A	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133B8AQ1
TMCS1133C1AQDVGRQ1	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133C1AQ1
TMCS1133C1AQDVGRQ1.A	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133C1AQ1
TMCS1133C2AQDVGRQ1	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133C2AQ1
TMCS1133C2AQDVGRQ1.A	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133C2AQ1
TMCS1133C3AQDVGRQ1	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133C3AQ1

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TMCS1133C3AQDVGRQ1.A	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133C3AQ1
TMCS1133C4AQDVGRQ1	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133C4AQ1
TMCS1133C4AQDVGRQ1.A	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133C4AQ1
TMCS1133C5AQDVGRQ1	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133C5AQ1
TMCS1133C5AQDVGRQ1.A	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133C5AQ1
TMCS1133C9AQDVGRQ1	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133C9AQ1
TMCS1133C9AQDVGRQ1.A	Active	Production	SOIC (DVG) 10	2000 LARGE T&R	Yes	SPOT AG (TOP SIDE)	Level-2-260C-1 YEAR	-40 to 125	1133C9AQ1

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF TMCS1133-Q1 :

- Catalog : [TMCS1133](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product